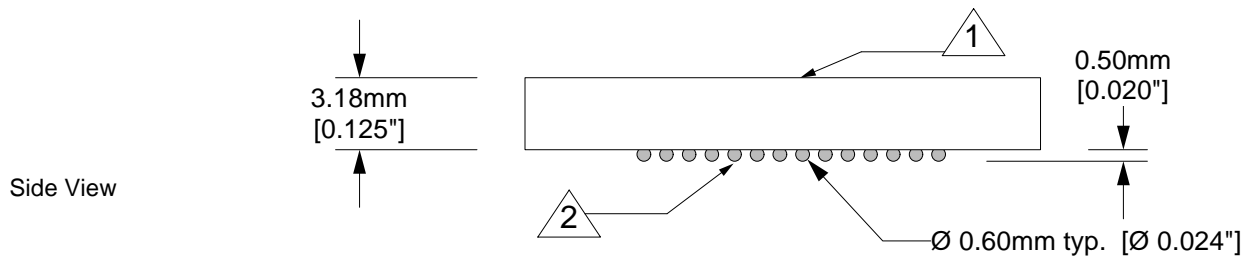
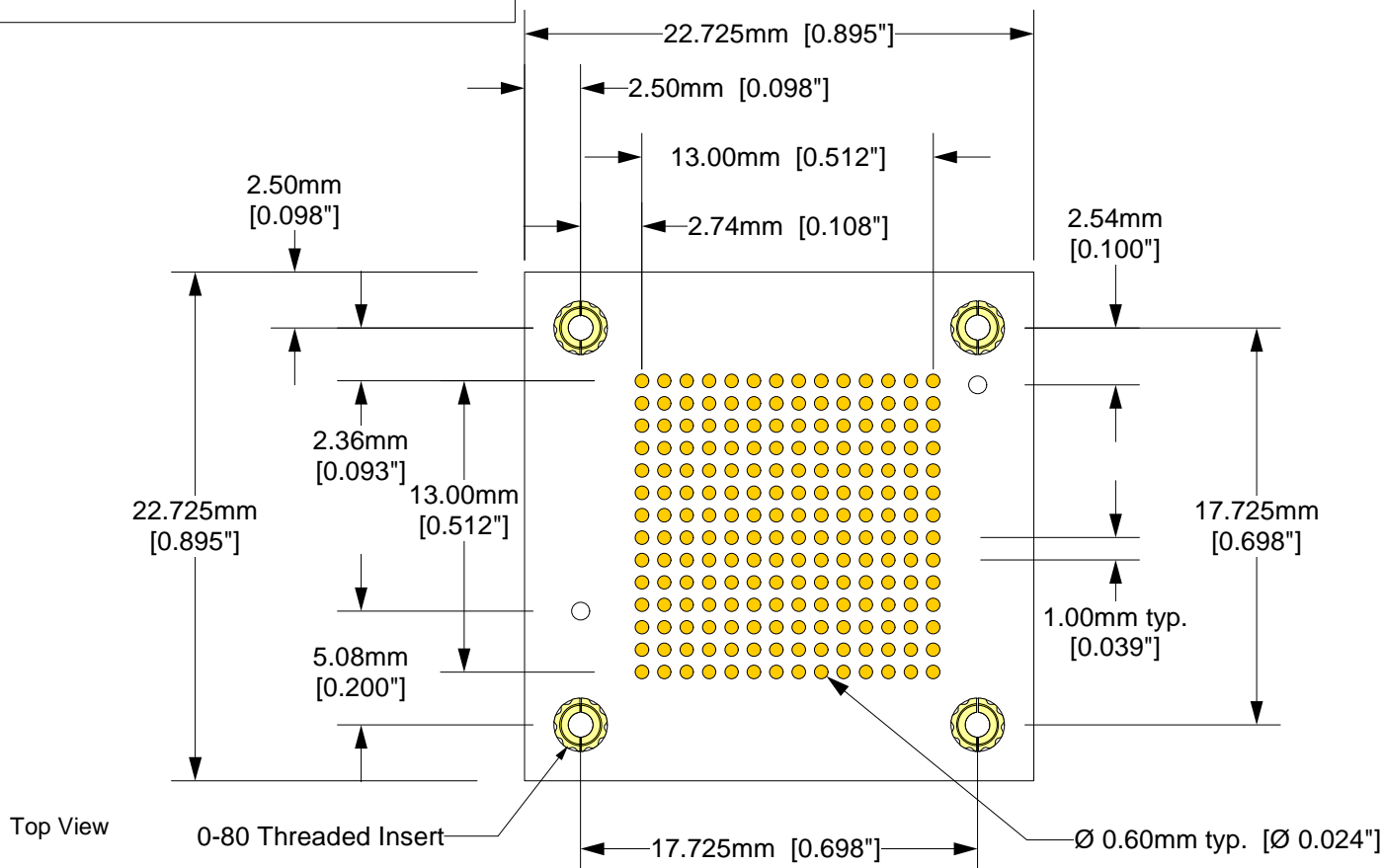



# RoHS COMPLIANT



- 1 Substrate: 3.18mm  $\pm$ 0.25mm [0.125"  $\pm$ 0.001"] FR4/G10 or equivalent high temp material. 17 $\mu$ m [1/2 oz.] Cu clad. Au plating. (RoHS)
- 2 Solder ball: Sn96.5Ag3.0Cu0.5

Description: BGA Surface Mount Adaptor  
 196 position surface mount land pattern to solder balls. To be used with GHz sockets.

Tolerances: diameters  $\pm$ 0.03mm [ $\pm$ 0.001"], PCB perimeters  $\pm$ 0.13mm [ $\pm$ 0.005"], PCB thicknesses  $\pm$ 0.18mm [ $\pm$ 0.007"], pitches (from true position)  $\pm$ 0.08mm [ $\pm$ 0.003"], all other tolerances  $\pm$ 0.13mm [ $\pm$ 0.005"] unless stated otherwise. Materials and specifications are subject to change without notice.

	<b>SF-BGA196C-B-05F Drawing</b> © 2006 IRONWOOD ELECTRONICS, INC. 11351 Rupp Dr. Suite 400 Burnsville MN 55337 Tele: (952) 229-8200 www.ironwoodelectronics.com	Status: Released	Scale: 3:1	Rev: A	
		Drawing: S.Natarajan		Date: 5/13/06	
		File: SF-BGA196C-B-05F Dwg		Modified:	